

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : TBD Confirmation No.: TBD
Applicant : Jeffrey A. West et al.
Filed : 10/30/2003
TC/A.U. : TBD
Examiner : TBD

Docket No. : TI-36238
Customer No. : 23494

Title : METHOD FOR IMPROVING RELIABILITY OF COPPER
INTERCONNECTS

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
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Dear Sir:

Please make the references listed on the enclosed PTO-1449 of record under 37 C.F.R. 1.56, 1.97, and 1.98 in the patent application identified above. Copies of the listed references are enclosed.

Respectfully submitted,



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					Complete If Known	
					Application Number	TBD
					Filing Date	10/30/2003
					First Named Inventor	Jeffrey A. West
					Group Art Unit	TBD
					Examiner Name	TBD
Sheet	1	of	1	Attorney Docket No.	TI-36238	

U.S. PATENT DOCUMENTS						
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	CA	T. TAKEWAKI et al., "Excellent Electro/Stress-Migration-Resistance Giant-Grain Copper Interconnect Technology for High-Performance Power Devices," Proceedings of 1995 International Symposium on Power Semiconductor Devices & ICs, Yokohama, pp. 438-442.				
	CB	S. HYMES et al., "Passivation of copper by silicide formation in dilute silane," J. Appl. Phys. 71 (9), 1 May 1992, pp. 4623-4625.				
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